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## **N-Channel Power MOSFET**

700V, 8A, 0.6Ω

#### **FEATURES**

- Super-Junction technology
- High performance due to small figure-of-merit
- High ruggedness performance
- High commutation performance

ΛD	DI	10/	TI	ON

- Power Supply
- Lighting

KEY PERFORMANCE PARAMETERS					
PARAMETER VALUE UNIT					
$V_{DS}$	700	V			
R <sub>DS(on)</sub> (max)	0.6	Ω			
$Q_g$	12.6	nC			



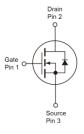












Notes: MSL 3 (Moisture Sensitivity Level) for TO-252 (D-PAK) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		SYMBOL	ITO-220	IPAK/DPAK	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	700		٧	
Gate-Source Voltage		V <sub>GS</sub>	±30		٧	
Continuous Drain Current (Note 1)	T <sub>C</sub> = 25°C		8 4.8		А	
Continuous Drain Current	T <sub>C</sub> = 100°C	I <sub>D</sub>				
Pulsed Drain Current (Note 2)		I <sub>DM</sub>	24		Α	
Total Power Dissipation @ $T_C = 25^{\circ}C$		P <sub>DTOT</sub>	32	83	W	
Single Pulsed Avalanche Energy (Note 3)		E <sub>AS</sub>	100		mJ	
Single Pulsed Avalanche Current (Note 3)		I <sub>AS</sub>	2		Α	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	- 55 to +150		ç	

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ITO-220	IPAK/DPAK	UNIT	
Junction to Case Thermal Resistance	R <sub>eJC</sub>	3.9	1.5	°C/W	
Junction to Ambient Thermal Resistance	$R_{\Theta JA}$	62		°C/W	

**Notes:**  $R_{\Theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\Theta JA}$  is guaranteed by design while  $R_{\Theta CA}$  is determined by the user's board design.  $R_{\Theta JA}$  shown below for single device operation on FR-4 PCB in still air.





<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV <sub>DSS</sub>	700			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, \ I_D = 250 \mu A$	$V_{GS(TH)}$	2	2.9	4	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I <sub>GSS</sub>			±100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 700V, V_{GS} = 0V$	I <sub>DSS</sub>			1	μΑ
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 4A$	R <sub>DS(on)</sub>		0.5	0.6	Ω
Dynamic (Note 5)						
Total Gate Charge	.,	$Q_g$		12.6		
Gate-Source Charge	$V_{DS} = 380V, I_D = 8A,$ $V_{GS} = 10V$	$Q_{gs}$		2.9		nC
Gate-Drain Charge		$Q_{gd}$		4.5		•
Input Capacitance	$V_{DS} = 100V, V_{GS} = 0V,$	C <sub>iss</sub>		743		
Output Capacitance	f = 1.0MHz	C <sub>oss</sub>		63		pF
Gate Resistance	F = 1MHz, open drain	$R_g$		3.19		Ω
Switching (Note 6)						
Turn-On Delay Time		t <sub>d(on)</sub>		21		
Turn-On Rise Time	$V_{DD} = 380V,$ $R_{GEN} = 25\Omega,$ $I_{D} = 8A, V_{GS} = 10V,$	t <sub>r</sub>		15		
Turn-Off Delay Time		t <sub>d(off)</sub>		40		ns
Turn-Off Fall Time	$I_D = OA$ , $V_{GS} = TUV$ ,	t <sub>f</sub>		9		
Source-Drain Diode (Note 4)						
Forward On Voltage	$I_{S} = 8A, V_{GS} = 0V$	V <sub>SD</sub>		0.84	1.4	V
Reverse Recovery Time	V <sub>B</sub> =200V, I <sub>S</sub> = 4A	t <sub>rr</sub>		187.9		ns
Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	Q <sub>rr</sub>		1.4		μC

#### Notes:

- 1. Current limited by package
- 2. Pulse width limited by the maximum junction temperature
- 3. L = 50mH,  $I_{AS} = 2A$ ,  $V_{DD} = 50V$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}C$
- 4. Pulse test: PW  $\leq$  300 $\mu$ s, duty cycle  $\leq$  2%
- 5. For DESIGN AID ONLY, not subject to production testing.
- 6. Switching time is essentially independent of operating temperature.





#### **ORDERING INFORMATION**

PART NO.	PACKAGE	PACKING
TSM70N600CI C0G	ITO-220	50pcs / Tube
TSM70N600CH C5G	TO-251 (IPAK)	75pcs / Tube
TSM70N600CP ROG	TO-252 (DPAK)	2,500pcs / 13" Reel

#### Note:

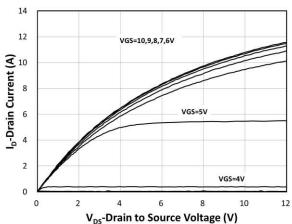
- 1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- 2. Halogen-free according to IEC 61249-2-21 definition



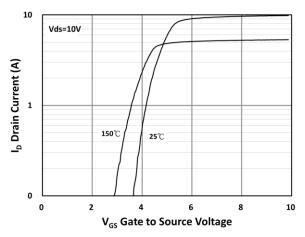
#### **CHARACTERISTICS CURVES**

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 

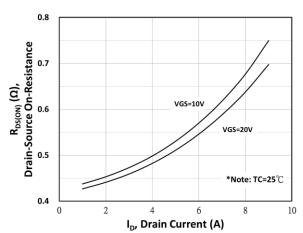
# **Output Characteristics**



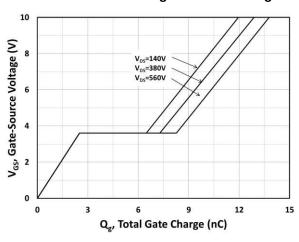
#### **Transfer Characteristics**



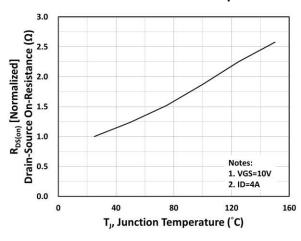
**On-Resistance vs. Drain Current** 



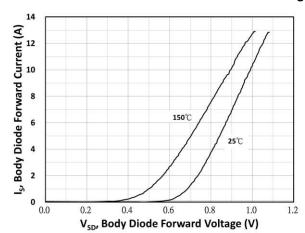
Gate-Source Voltage vs. Gate Charge



**On-Resistance vs. Junction Temperature** 



Source-Drain Diode Forward Current vs. Voltage

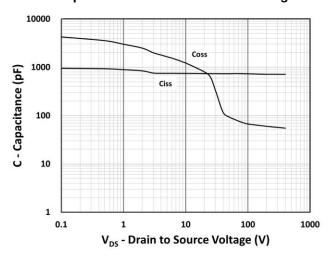




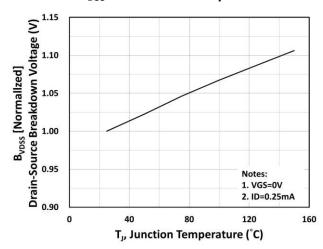
#### **CHARACTERISTICS CURVES**

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 

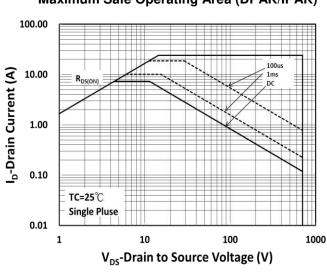
#### Capacitance vs. Drain-Source Voltage



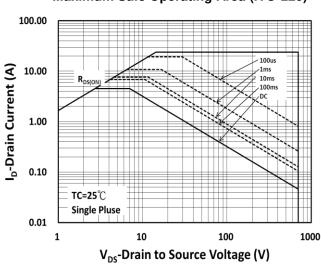
#### BV<sub>DSS</sub> vs. Junction Temperature



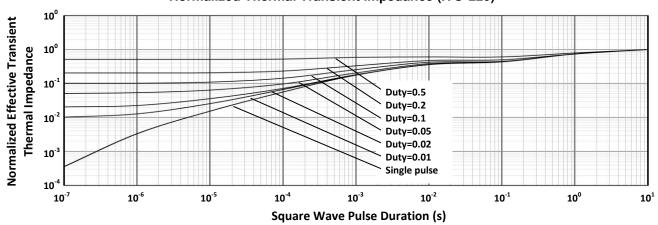
#### Maximum Safe Operating Area (DPAK/IPAK)



**Maximum Safe Operating Area (ITO-220)** 



#### Normalized Thermal Transient Impedance (ITO-220)



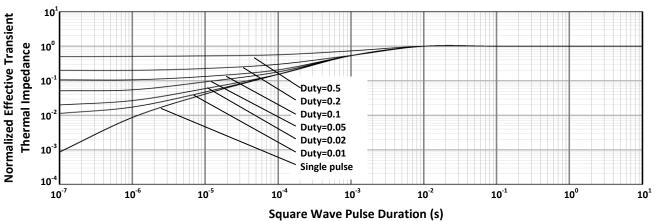
Version: E1706



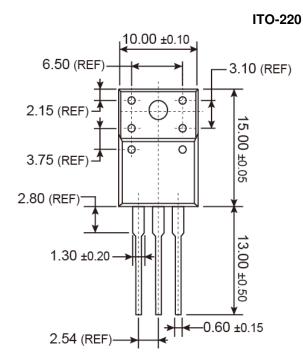
#### **ELECTRICAL CHARACTERISTICS CURVES**

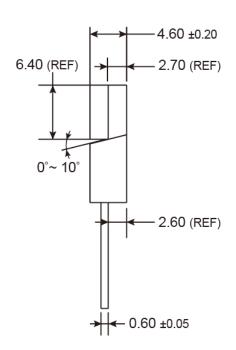
(T<sub>C</sub> = 25°C unless otherwise noted)

### Normalized Thermal Transient Impedance (DPAK/IPAK)









#### **MARKING DIAGRAM**



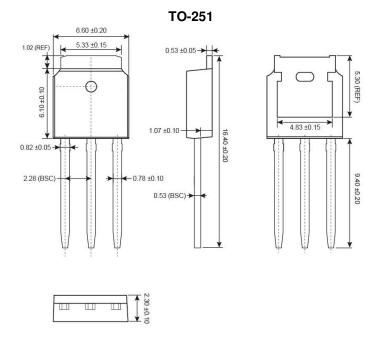
**G** = Halogen Free

Y = Year Code

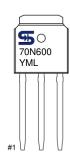
WW = Week Code (01~52)

F = Factory Code





#### **MARKING DIAGRAM**



Y = Year Code

M = Month Code for Halogen Free Product

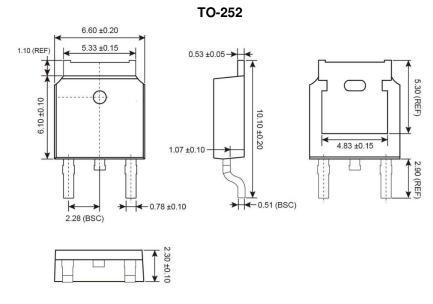
 $\mathbf{O}$  =Jan  $\mathbf{P}$  =Feb  $\mathbf{Q}$  =Mar  $\mathbf{R}$  =Apr

S = May T = Jun U = Jul V = Aug

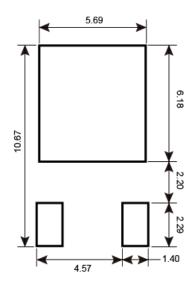
W = Sep X = Oct Y = Nov Z = Dec

**L** = Lot Code  $(1\sim9, A\sim Z)$ 





#### SUGGESTED PAD LAYOUT (Unit: Millimeters)



#### **MARKING DIAGRAM**



Y = Year Code

**M** = Month Code for Halogen Free Product

O =Jan P =Feb Q =Mar R =Apr

S = May T = Jun U = Jul V = Aug

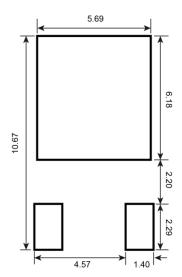
W = Sep X = Oct Y = Nov Z = Dec

 $L = \text{Lot Code } (1 \sim 9, A \sim Z)$ 



TO-252 6.57 ±0.16 1.08 ±0.19 0.515 ±0.065 5.34 ±0.13 5.3 (MIN) 6.11 ±0.11  $-0.825 \pm 0.185$  $9.9 \pm 0.5$ 0.127 (MAX) 2.743 0.525 ±0.075 0.955 ±0.185 -1.585 ±0.185 0.76 ±0.12 0.508 (BSC) 2.286 (BSC)

#### SUGGESTED PAD LAYOUT (Unit: Millimeters)



#### **MARKING DIAGRAM**



Y = Year Code

**M** = Month Code for Halogen Free Product

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L = Lot Code (1~9, A~Z)



Taiwan Semiconductor

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